

HOUSING MATERIAL : THERMOPLASTIC POLYESTER UL94V0; GREY

HOUSING CAN WITHSTAND EXPOSURE TO LEAD FREE WAVE SOLDERING TEMPERATURE OF 260-265°C

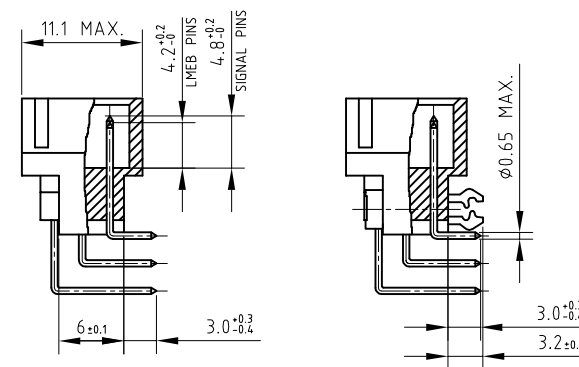
WHEN USED WITH PROTECTIVE ADHESIVE OR PROTECTIVE METALLIC DEVICE FOR ANGLE CONNECTORS

AS IT IS USED IN CLASSICAL LEAD WAVE SOLDERING AT 235-250°C.

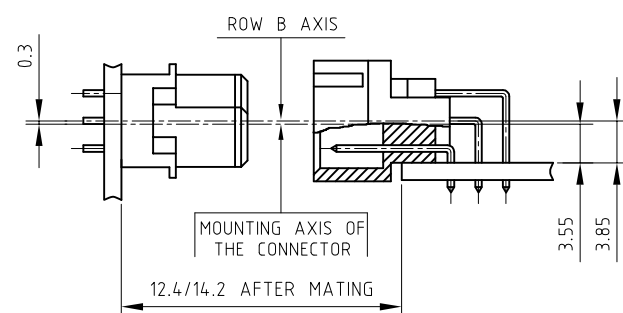
CONTACT & HARPOON MATERIAL	:	COPPER ALLOY
CONTACT ACTIVE ZONE PLATING	:	Au OVER Ni (or) Au+Pd-Ni OVER Ni
CONTACT TERMINATION ZONE PLATING	:	Sn (PURE MATT) OVER Ni
HARPOON PLATING	:	Sn (PURE MATT) OVER Ni

CURRENT RATING AT 20°C	:	1.5 A
CURRENT (I MAX)	:	2 A
TEMPERATURE RANGE	:	-55°C TO +125°C
CONTACT RESISTANCE	:	≤ 20 mΩ
INSULATION RESISTANCE	:	≥ 10 ⁶ MΩ
TEST VOLTAGE (rms)	:	1000 V

INSERTION FORCE PER CONTACT	:	≤ 0.94 N
EXTRACTION FORCE PER CONTACT	:	≥ 0.15 N
REFERENCE SPECIFICATION	:	DIN 41612 (or) IEC 603-2



Technical drawing of a plate with 32 holes. The drawing shows a top view of the plate with a central break. The plate has a width of 100 mm and a length of 88.9 mm. The holes are arranged in two rows of 16 holes each. The center-to-center distance between holes in a row is 2.54 mm. The distance from the center of the first hole to the edge of the plate is 5.3 mm. The distance from the center of the last hole to the edge of the plate is 5.08 mm. The hole diameter is $\varnothing 1.0 \pm 0.1$ mm. The plate thickness is 0.1 mm. The drawing includes dimension lines, arrows, and tolerances.



1. THE "LF" PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
2. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 3.5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 MM MINIMUM THICK CIRCUIT BOARD.
3. LEAD FREE OR RoHS DIRECTIVE LABELING TO BE PROVIDED AS PER GS-14-920 FOR LEAD FREE VERSION.

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